



RoHS Material Declaration Certificate

HMS Industrial Networks hereby states that all standard products, per the below table, are compliant to the European Union directive 2015/863/EU * (RoHS III). Each of the component material in an HMS product is assessed in accordance with HMS procedures for approval of material. HMS use documents (such as material declaration or other information) and contractual agreements to evaluate compliance and approve new materials and components. HMS's RoHS compliant products are manufactured in lead free processes.

Product category (Product line)	Product group (family)	Product category (Product line)	Product group (family)
Anybus Embedded	Anybus-IC	Ixxat Machine Comms/HW	CAN Interfaces
	Anybus-IP		CAN Topology Components
	Anybus-M		CAN Diagnostic Products
	Anybus-S		CAN IO Modules
	Anybus-S Drive Profile		CAN-IE Gateways
	Anybus CompactCom B30, C30, M30, B40, C40, M40		CAN Cables & Accessories
	Anybus CompactCom Drive Profile		CBT & CANobserver
Anybus Gateways	Anybus Communicator	Ixxat Automotive	Econ 100
	Anybus .Net gateway		INpact
	Anybus X-gateway		Powerlink HW
	Ethernet/IP Linking Devices		CM-CANopen
Anybus Wireless	Anybus Wireless Bridge	Ixxat Safety	IXXAT 1SI CANopen
	Anybus Wireless Bolt		IXXAT SG-gateways
Remote Access	eWON Cosy	FRC-HW & Bundles	
Remote Data	eWON Flexy	Automotive Cables & Accessories	
Remote Networks	eWON eFive	Rest Bus Sim & Gateway SW	
Remote Management	eWON Netbiter	Safe T100	

Halmstad 2019-05-08

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** This statement is based on information and data provided from 3rd parties and may not have been verified through destructive testing methods or other chemical analysis. Most of HMS's products contain one or more components that have a RoHS exemption at a concentration of more than 0.1% w/w. When that is a case, one of the following exemption may apply: 6(c) - "Copper alloy containing up to 4% lead by weight, 7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead) 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezo electronic devices, or in a glass or ceramic matrix compound. Under normal and reasonably foreseeable circumstances of application, the supplied goods shall not release any substances during its lifetime.*

HMS reserves the right to change the information stated in this document without any further notice.